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On page 3, lines 1-2, please amend the paragraph as follows:

42 voids that would be easily subjected to popcorn effect and delamination, thus degrading the quality and reliability of the finished TCP product.

REMARKS

Claims 1-12 are pending in the application. Claims 1, 5, and 6 have been rejected under 35 USC 102(c). Claims 2-4 and 7-12 have been rejected under 35 USC 103(a).

As an initial matter, the specification has been amended to correct minor errors. On page 1, last paragraph, the text provided therein is duplicated at the top of page 2, and thus has been deleted. On page 2, a typographical error in the designation of FIG. 1C has been corrected. On page 3, line 1, the text has been amended in accordance with page 3, lines 9-10, to provide correct sentence structure. No new matter is added.

Applicants claim a tape carrier package structure, including a semiconductor chip with a plurality of dummy pads arranged on the corners thereof and a group of dummy leads bonded between the dummy pads and corner-situated lead bonding areas on the tape carrier, for providing firm support to the four corners of the semiconductor chip.

As shown in FIG. 2B, a group of I/O leads 231 are positioned along the sides of the semiconductor chip 210, and the dummy leads 232 are positioned in the corners thereof. Corner-situated bonding areas 222 can provide firm support to the semiconductor chip.

The above-described semiconductor package structure can yield significant benefits. By including localized corner-situated lead-bonding areas, firm support is provided to the semiconductor chip, thereby reinforcing the mounting of the semiconductor chip on the tape carrier. Such reinforcement can help prevent cracking of the I/O leads during a lead bonding process.

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Claims 1, 5, and 6 were rejected under 35 USC 102(e) as being anticipated by U.S. Patent 6,268,644 to Umehara et al. (hereinafter "Umehara"). Claims 2-4 and 7-12 have been rejected under 35 USC 103(a) as being unpatentable over Umehara. For convenience, these rejections are addressed together.

Umehara fails to teach or suggest the use of corner-situated lead-bonding areas to provide firm support to the corners of a semiconductor chip. In Umehara, dummy wires 17 are provided as "dam members" to suppress the flow velocity of molding resin in order to prevent adjacent wires from short circuiting (see column 2, lines 40-44). There is no teaching or suggestion for providing structural reinforcement to the corners of a semiconductor chip, and the dummy wires of Umehara are not useful for this purpose. Therefore, Umehara fails to teach or suggest corner-situated lead-bonding areas as described in the Applicants' invention.

Accordingly, the rejection should be withdrawn. See, for instance, *In re Marshall*, 198 USPQ at 346 ("[r]ejections under 35 USC 102 are proper only when the claimed subject matter is identically disclosed or described in the prior art.").

It is believed the application is in condition for immediate allowance, which action is earnestly solicited.

Respectfully submitted,



Peter F. Corless (Reg. No. 33,860)
Steven M. Jensen (Reg. No. 42,693)
Dike Bronstein, Roberts & Cushman
Intellectual Property Practice Group
EDWARDS & ANGELL, LLP
P.O. Box 9169
Boston, MA 02209
(617) 439-4444

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APPENDIX A:
VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE SPECIFICATION

On page 1, lines 25-26, the last paragraph should be deleted.

(The following text is deleted: "Referring further to FIG. 1B, the conventional TCP structure is constructed on a tape carrier 120, such as TAB tape, which is formed with a centrally-located device hole")

On page 2, lines 11-14, the paragraph should be amended as follows:

Referring further to FIG. [1D] 1C, in the next step, an encapsulation process is performed to dispense an encapsulation material, such as resin, through the gaps between the inner leads 130 into the device hole 120a so as to form an encapsulation body 140 to encapsulate the semiconductor chip 110.

On page 3, lines 1-2, the first paragraph should be amended as follows:

[140] voids that would be easily subjected to popcorn effect and delamination, thus degrading the quality and reliability of the finished TCP product.